SLOVENSKI STANDARD
SIST EN 60191-6-16:2008

01-januar-2008

Mehanska standardizacija polprevodniških elementov - 6-16. del: Pojmovnik polprevodniških preskušanj in podstavkov za utekanje za BGA, LGA, FBGA in FLGA (IEC 60191-6-16:2007)

Mechanical standardization of semiconductor devices -- Part 6-16: Glossary of semiconductor tests and burn-in sockets for BGA, LGA, FBGA and FLGA

Mechanische Normung von Halbleiterbauelementen -- Teil 6-16: Glossar für Fassungen für die Prüfung und Voralterung von BGA, LGA, FBGA und FLGA

Normalisation mécanique des dispositifs à semi-conducteurs - Partie 6-16 : Glossaire des supports de test et de déverminage pour les BGA, LGA, FBGA et FLGA

Ta slovenski standard je istoveten z: EN 60191-6-16:2007

ICS:

01.100.25	Risbe s področja elektrotehnike in elektronike	Electrical and electronics engineering drawings
31.080.01	Polprevodniški elementi (naprave) na splošno	Semiconductor devices in general
31.240	Mehanske konstrukcije za elektronsko opremo	Mechanical structures for electronic equipment

SIST EN 60191-6-16:2008 **en,de**

EUROPEAN STANDARD
NORME EUROPÉENNE
EUROPÄISCHE NORM

EN 60191-6-16

June 2007

ICS 31.080.01

English version

Mechanical standardization of semiconductor devices - Part 6-16: Glossary of semiconductor tests and burn-in sockets for BGA, LGA, FBGA and FLGA

(IEC 60191-6-16:2007)

Normalisation mécanique
des dispositifs à semi-conducteurs -
Partie 6-16: Glossaire des supports
de test et de déverminage
pour les BGA, LGA, FBGA et FLGA
(CEI 60191-6-16:2007)

Mechanische Normung
von Halbleiterbauelementen -
Teil 6-16: Glossar für Fassungen
für die Prüfung und Voralterung
von BGA, LGA, FBGA und FLGA
(IEC 60191-6-16:2007)

This European Standard was approved by CENELEC on 2007-05-01. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

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CENELEC
European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

Central Secretariat: rue de Stassart 35, B - 1050 Brussels

Ref. No. EN 60191-6-16:2007 E

Foreword

The text of document 47D/679/FDIS, future edition 1 of IEC 60191-6-16, prepared by SC 47D, Mechanical standardization for semiconductor devices, of IEC TC 47, Semiconductor devices, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 60191-6-16 on 2007-05-01.

The following dates were fixed:

– latest date by which the EN has to be implemented at national level by publication of an identical national standard or by endorsement	(dop)	2008-02-01
– latest date by which the national standards conflicting with the EN have to be withdrawn	(dow)	2010-05-01

Annex ZA has been added by CENELEC.

Endorsement notice

The text of the International Standard IEC 60191-6-16:2007 was approved by CENELEC as a European Standard without any modification.

Annex ZA
(normative)

Normative references to international publications with their corresponding European publications

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

Publication	Year	Title	EN/HD	Year
IEC 60191-1	1966	Mechanical standardization of semiconductor devices - Part 1: Preparation of drawings of semiconductor devices	-	-
IEC 60191-2	1966	Mechanical standardization of semiconductor devices - Part 2: Dimensions	-	-
IEC 60191-3	1999	Mechanical standardization of semiconductor devices - Part 3: General rules for the preparation of outline drawings of integrated circuits	EN 60191-3	1999
IEC 60191-4	1999	Mechanical standardization of semiconductor devices - Part 4: Coding system and classification into forms of package outlines for semiconductor device packages	EN 60191-4	1999

INTERNATIONAL STANDARD

IEC 60191-6-16

First edition
2007-04

Mechanical standardization of semiconductor devices –

Part 6-16:
Glossary of semiconductor tests and burn-in sockets for BGA, LGA, FBGA and FLGA

Commission Electrotechnique Internationale
International Electrotechnical Commission
Международная Электротехническая Комиссия

PRICE CODE L

For price, see current catalogue

INTERNATIONAL ELECTROTECHNICAL COMMISSION

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MECHANICAL STANDARDIZATION OF SEMICONDUCTOR DEVICES –

Part 6-16: Glossary of semiconductor tests and burn-in sockets for BGA, LGA, FBGA and FLGA

FOREWORD

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International Standard IEC 60191-6-16 has been prepared by subcommittee 47D: Mechanical standardization of semiconductor devices, of IEC technical committee 47: Semiconductor devices.

The text of this standard is based on the following documents:

FDIS	Report on voting
47D/679/FDIS	47D/683/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directive, Part 2.

A list of all the parts of the IEC 60191 series, under the general title *Mechanical standardization of semiconductor devices*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the maintenance result date indicated on the IEC web site under "http://webstore.iec.ch" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.